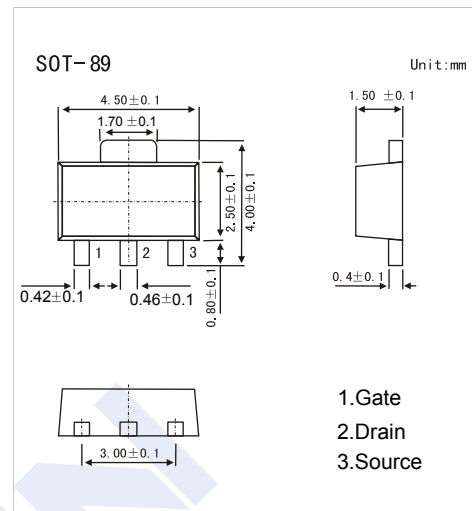
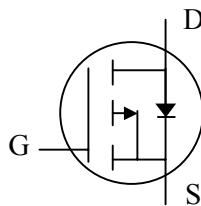


## P-Channel Enhancement MOSFET

## KX9435

## ■ Features

- $V_{DS} (V) = -30V$
- $I_D = -4.2 A (V_{GS} = -10V)$
- $R_{DS(ON)} < 55m\Omega (V_{GS} = -10V)$
- $R_{DS(ON)} < 90m\Omega (V_{GS} = -4.5 V)$
- Low Gate Charge
- Fast Switching Characteristic

■ Absolute Maximum Ratings  $T_a = 25^\circ C$ 

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	$T_a = 25^\circ C$ *	-4.2
		$T_a = 70^\circ C$ *	-3.4
Pulsed Drain Current	$I_{DM}$	-20	A
Power Dissipation	$P_D$	1.25	W
Linear Derating Factor		0.01	W/ $^\circ C$
Thermal Resistance.Junction- to-Ambient	$R_{thJA}$	100	$^\circ C/W$
Junction Temperature	$T_J$	150	$^\circ C$
Junction and Storage Temperature Range	$T_{stg}$	-55 to 150	

\*. Surface mount on FR4 board,  $t < 10s$ .

## P-Channel Enhancement MOSFET

## KX9435

## ■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =-250 μ A, V <sub>GS</sub> =0V	-30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C			-1	μ A
		V <sub>DS</sub> =-24V, V <sub>GS</sub> =0V, T <sub>J</sub> =70°C			-25	
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =± 20V			± 100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250 μ A	-1		-3	V
Static Drain-Source On-Resistance *1	R <sub>DS(on)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-4A			55	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-2A			90	
Forward Transconductance *1	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-4A		6		S
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =-25V, f=1MHz		520	830	pF
Output Capacitance	C <sub>oss</sub>			180		
Reverse Transfer Capacitance	C <sub>rss</sub>			130		
Gate resistance	R <sub>g</sub>	f=1MHz		16	24	Ω
Total Gate Charge *1	Q <sub>g</sub>	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-25V, I <sub>D</sub> =-4A		10	16	nC
Gate Source Charge	Q <sub>gs</sub>			2		
Gate Drain Charge	Q <sub>gd</sub>			6		
Turn-On DelayTime *1	t <sub>d(on)</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>D</sub> =15 Ω ,R <sub>G</sub> =3.3 Ω  I <sub>D</sub> =1.0A		6.3		ns
Turn-On Rise Time	t <sub>r</sub>			3.2		
Turn-Off DelayTime	t <sub>d(off)</sub>			38.3		
Turn-Off Fall Time	t <sub>f</sub>			12		
Body Diode Reverse Recovery Time	t <sub>rr</sub>			30		
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>S</sub> =-4A, V <sub>GS</sub> =0, di/dt=100A/ μ s		24		nC
Maximum Body-Diode Continuous Current	I <sub>S</sub>				-1	A
Diode Forward Voltage *1	V <sub>SD</sub>	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V			-1.3	V

\*1.Pulse width &lt;300us , duty cycle &lt;2%.

# P-Channel Enhancement MOSFET

## KX9435

### ■ Typical Characteristics

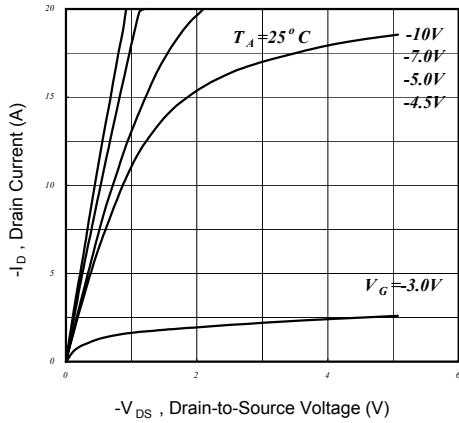


Fig 1. Typical Output Characteristics

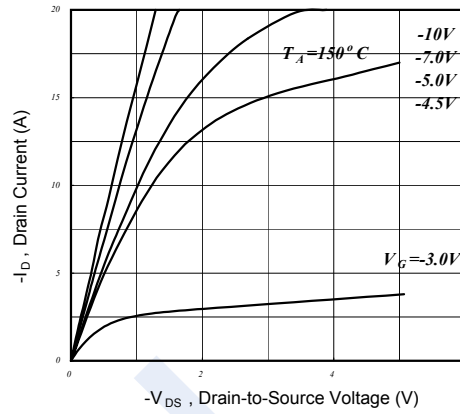


Fig 2. Typical Output Characteristics

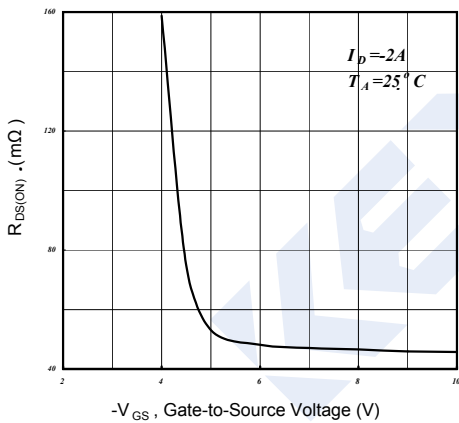


Fig 3. On-Resistance v.s. Gate Voltage

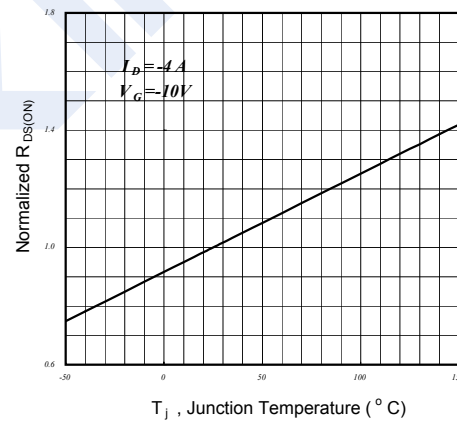


Fig 4. Normalized On-Resistance v.s. Junction Temperature

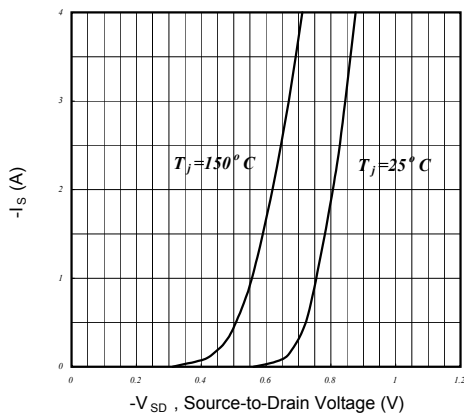


Fig5. Forward Characteristic of Reverse Diode

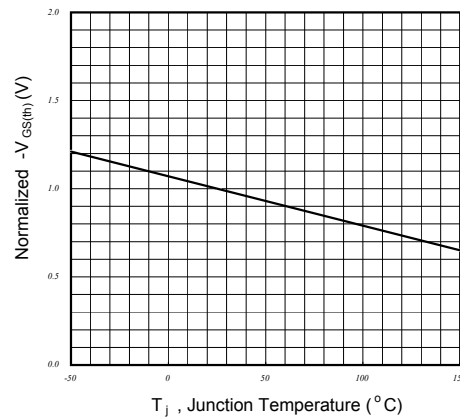


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

# P-Channel Enhancement MOSFET

## KX9435

### Typical Characteristics

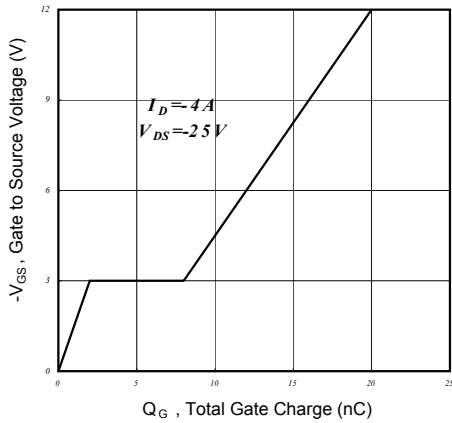


Fig 7. Gate Charge Characteristics

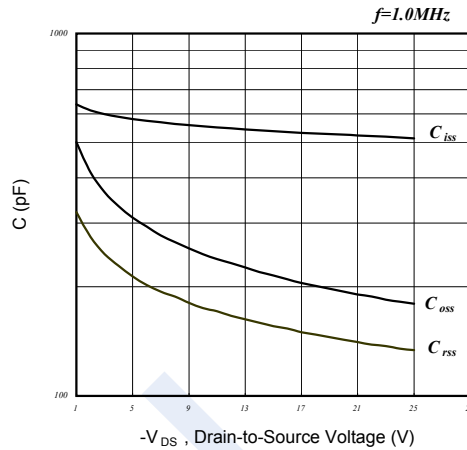


Fig 8. Typical Capacitance Characteristics

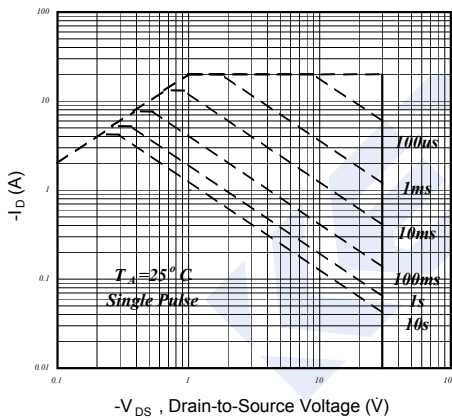


Fig 9. Maximum Safe Operating Area

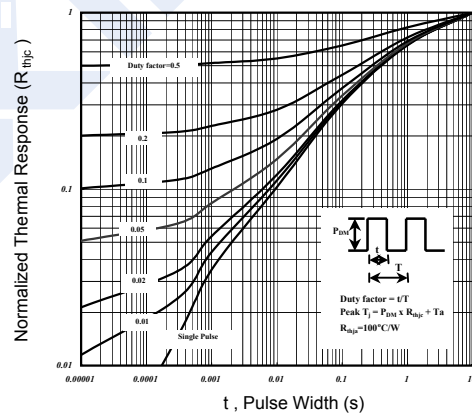


Fig 10. Effective Transient Thermal Impedance

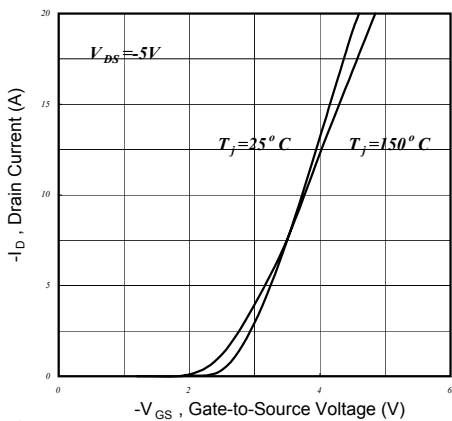


Fig 11. Transfer Characteristics

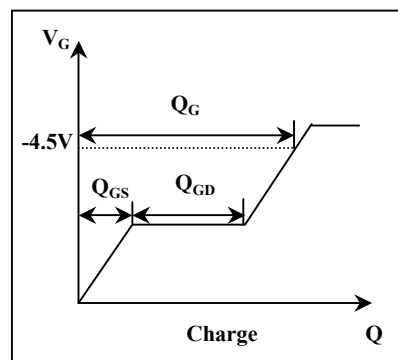


Fig 12. Gate Charge Waveform